


MATERIAL DECLARATION SHEET



Material Number	MH1608 T Series			
Product Line	Ferrite Chip Bead			
Compliance Date	2022/03/04			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite body	Ferrite Ni-Zn Series	0.005369	Iron oxide	1309-37-1	62.000	51.212	83.50
				Nickel oxide	1313-99-1	11.000	9.086	
				Zinc oxide	1314-13-2	20.000	16.520	
				Copper oxide	1317-38-0	7.000	5.782	
		Bismuth Trioxide	0.0000585	Bismuth trioxide	1304-76-3	100.000	0.900	
2	Internal Circuit	Metallic conductor paste	0.0007475	Silver	7440-22-4	97.326	11.192	11.50
				Resins	9004-57-3	2.674	0.308	
3	Terminal	Silver paste_DP4337W	0.000195	Silver	7440-22-4	74.074	2.222	3.00
				Silicon dioxide	60676-86-0	12.346	0.370	
				Resins	9004-57-3	12.346	0.370	
				Titanium dioxide	13463-67-7	1.234	0.037	
4	Solder Base	S Nickel Pellets	0.000065	Nickel	7440-02-0	100.000	1.000	1.00
5	Solder	Lead Free Solder	0.000065	Tin	7440-31-5	100.000	1.000	1.00
Total weight			0.0065					

This Document was updated on: 2022/03/04

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.